

Appln No. 10/028,745

Amdt date January 5, 2004

Reply to Office action of August 4, 2003

Amendments to the Specification:

Please amend the paragraph beginning at page 7, line 21 as follows:

As can be seen more clearly in Figure 2, which shows the casing 10 without the top cover 12 (see Figure 1) and with components e.g. 30 of WDM add/drop unit inserted, the casing 10 further comprises a backplane in the form of a mother board 32, for connection and interconnection of the inserted components e.g. 30, 34, and 36. The functionality of the various components will be described later with reference to Figures 9 and 10 and 11. It is noted that in the embodiment shown in Figure 2, the casing 10 is designed in a manner such that the heat sink openings 38 and 42, and the backplane 32 are mirrored with respect to a centreplane halfway along the width of the casing 10. This enables an optimal spacing between the set of fins 44, 46, and 48. At the same time, to facilitate that components 30 and 34, which, in end use, have different functionality and specifications, may initially undergo the same manufacturing steps and can be manufactured along the same production line up to a certain step, the components 30 and 34 are inserted with a "swapped" orientation. In other words, in terms of the individual chassis/housing of the components, 30 and 34, they are disposed upside down with respect to each other. To prevent inadvertent insertion of the wrong component, the electrical connections to the backplane 32 are keyed appropriately. Overall, the components 30, 34 are thus hot-swappable on-site.